1. **DESCRIPTION**

The XD07 and XL07Z devices offer low offset and long-term stability by means of a low-noise, chopperless, bipolar-input-transistor amplifier circuit. For most applications, external components are not required for offset nulling and frequency compensation. The true differential input, with a wide input-voltage range and outstanding common- mode rejection, provides maximum flexibility and performance in high-noise environments and in noninverting applications. Low bias currents and extremely high input impedances are maintained over the entire temperature range.

2. FEATURES

- Low noise
- No external components required
- Replace chopper amplifiers at a lower cost
- Wide input-voltage range:

0 V to ±14 V (typ, ±15-V supply)

• Wide supply-voltage range: ±3 V to ±18V



3. PIN CONFIGURATIONS AND FUNCTIONS

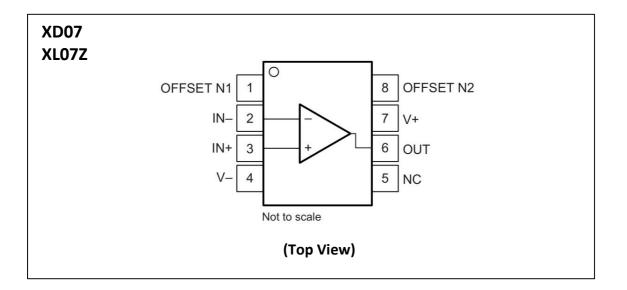
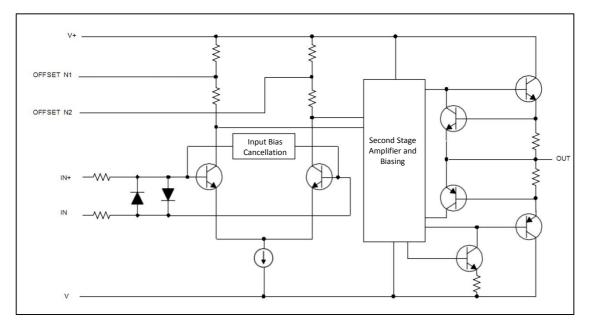


Table 2. Pin Functions

PIN			
NAME	NO.	ТҮРЕ	DESCRIPTION
OFFSET N1	1	Input	External input offset voltage adjustment
IN-	2	Input	Inverting input
IN+	3	Input	Noninverting input
V-	4	_	Negative supply
NC	5	_	Do not connect
OUT	6	Output	Output
V+	7	_	Positive supply
OFFSET N2	8	Input	External input offset voltage adjustment



4. FUNCTIONAL BLOCK DIAGRAM



Block Diagram

REMARK:

- The input offset voltage of operational amplifiers (op amps) arises from unavoidable mismatches in the differential input stage of the op-amp circuit caused by mismatched transistor pairs, collector currents, current- gain betas (β), collector or emitter resistors, and so on. The input offset pins allow the designer to adjust for these mismatches by external circuitry.
- 2) The slew rate is the rate at which an operational amplifier can change the output when there is a change on the input. The XL07Z have a 0.3-V/µs slew rate.
- 3) The XL07Z are powered on when the supply is connected. The devices can be operated as single-supply operational amplifiers or dual-supply amplifiers, depending on the application.

5. SPECIFICATIONS

5.1. Absolute Maximum Ratings⁽¹⁾

			MIN	MAX	UNIT	
	Supply voltage ⁽²⁾	Single supply		40	N.	
Vs	Supply voltage ⁽²⁾	Dual supply		±20	· ·	
		Differential ⁽³⁾		±28		
	Input voltage	Single-ended ⁽⁴⁾		±20	V	
	Output short-circuit ⁽⁵⁾		Con	tinous		
Tj	Operating junction temperature		-40	85	°C	
T _{stg}	Storage temperature		-55	125	°C	

[1] Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- [2] All voltage values, unless otherwise noted, are with respect to the midpoint between V+ and V-.
- [3] Differential voltages are at IN+ with respect to IN-.
- [4] The magnitude of the input voltage must never exceed the magnitude of the supply voltage or 15 V, whichever is less.
- [5] The output can be shorted to ground or to the negative power supply. Fast ramping shorts to the positive supply can cause permanent damage and eventual destruction.





5.2. Thermal Resistance Characteristics

		XL07Z	XD07	
THERMAL METRIC		D (SOP)	P (DIP)	UNIT
		8 PINS	8 PINS	- CNIT
R _{θJA}	Junction-to-ambient thermal resistance	127.6	85	°C/W
R _{0JC(top)}	Junction-to-case (top) thermal resistance	67.1	68.6	°C/W
R _{θJB}	Junction-to-board thermal resistance	71.4	55.6	°C/W
τιΨ	Junction-to-top characterization parameter	18.7	38.3	°C/W
ψ _{JB}	Junction-to-board characterization parameter	70.6	55.2	°C/W
R _{0JC(bot)}	Junction-to-case (bottom) thermal resistance	-	_	°C/W

5.3. ESD Ratings

			VALUE	UNIT				
V(ccp)	Flastrastatia disabarga	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 $^{(1)}$	±1000	N				
V(ESD)	Electrostatic discharge	Charged-devicemodel (CDM), per JEDEC specification JESD22-C101 ⁽²⁾	±1000	v				
[1] IED	1] IEEEC document IEEISS states that 500-V HBM allows safe manufacturing with a standard ESD control process							

[1] JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

[2] JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

5.4. Recommended Operating Conditions

			MIN	NOM MAX	UNIT
N Currelinghtere	Cupply voltogo	Single supply	6	36	V
Vs	Supply voltage	Dual supply	±3	±18	v
VCM	Common-mode input voltage	V _s = ±15 V	-13	13	V
T _A	Operating ambient temperature		-40	85	°C

5.5. Electrical Characteristics

at TA = 25°C, VS = \pm 15 V, RL = 2 k Ω connected to mid-supply, and VCM = VOUT = mid-supply (unless otherwise noted)

	PARAMETER TEST CONDITIONS		MIN	ТҮР	MAX	UNIT		
OFFSET VC	DLTAGE							
		XD07			±60			
Vos	Input offset voltage	XD07	T _A = -40°C to 85°C		±85		μV	
VUS	input onset voltage	XL07Z				±150	μν	
		XL072	T _A = -40°C to 85°C			±250		
dV _{os} /dT	Input offset voltage drift	T _A = -40°C to 85°C	XD07		±0.5		μV/°C	
uvos/ur	input onset voltage unit	T _A = -40 C to 85 C	XL07Z			±2.5	μν/ ς	
	Long-term drift of input offset voltage				±0.4		μV/mo	
	Offset adjustment range	R _s = 20 kG	2		±4		mV	
PSRR	Power supply rejection	Vs = ±3 V to ±18 V			7	32	μν/ν	
PSKK	ratio	VS = I3 V 10 I18 V	T _A = -40°C to 85°C		10	51		
INPUT BIA	S CURRENT							
		XD07			±1.8		- nA	
IB	Input bias current		T _A = -40°C to 85°C		±2.2			
ιB	input bias current	XL07Z				±12		
		XL07Z	$T_A = -40^{\circ}C \text{ to } 85^{\circ}C$			±14		
	Input bias current drift	XD07			±18		pA/°C	
	input bias current unit	XL07Z				±50	рау с	
		VD07			±0.8			
loc	Input offset surrent	XD07	T _A = -40°C to 85°C		±1.6		-	
IOS	Input offset current	XL07Z				±6	nA	
		ALU/Z	T _A = -40°C to 85°C			±8	8	
		XD07			12		- 4 /80	
	Input offset current drift	XL07Z				±50	pA/°C	



Electrical Characteristics (continued)

	PARAMETER	TEST CONDITIO	NS	MIN	ТҮР	MAX	UNIT	
NOISE								
	Input voltage noise	f = 0.1 Hz to 10 H	łz		0.38		μV_{PP}	
		f = 10 Hz			10.5			
e _N	Input voltage noise density	f = 100 Hz			10.2		nV/vHz	
	densky	f = 1 kHz			9.8		110/0112	
	Input current noise	f = 0.1 Hz to 10 Hz			15		pA_{pp}	
		f = 10 Hz			0.35			
i _N	Input current noise density	f = 100 Hz			0.15		pA/√Hz	
	densky	f = 1 kHz			0.13		pAy V112	
INPUT VO	LTAGE RANGE							
Ven				±13	±14			
VCM	Common-mode voltage	T _A = -40°C to 85°	°C	±13	±13.5		V	
		XD07		100	120			
		$V_{CM} = \pm 13 V$	T _A = -40°C to 85°C	97	120		dD	
CMRR	Common-mode rejection	XL07Z		94	110		dB	
	ratio	V _{CM} = ±13 V	T _A = -40°C to 85°C	94	106			
INPUT CA	PACITANCE							
rı	Input resistance			7	33		MΩ	
OPEN-LO	OP GAIN							
			XD07	100	400			
		$1.4 V < V_0 < 11.4 V, R_L = 500 k\Omega$	XL07Z		400			
AOL	Open-loop voltage gain			120	400		V/mV	
		V ₀ = ±10 V	T _A = -40°C to +85°C	100	400			
FREQUEN	CY RESPONSE							
	Unity gain bandwidth			0.4	0.6		MHz	
SR	Slew rate	$V_{s} = 5 V, R_{L} = 2 k$	Ω		0.3		V/µs	
OUTPUT								
				±11.5	±12.8			
	Voltago output gy in-	T _A = -40°C to 85°C		±11	±12.6		v	
	Voltage output swing	$R_L = 10 \ k\Omega$		±12	±13		v	
		$R_L = 1 \ k\Omega$			±12			
POWER S	UPPLY							
	Dowor dissignation	No load			80	150		
PD	Power dissipation	V _s = ±3 V, no loa	d		4	8	mW	

[1] The specifications listed in the Electrical Characteristics apply to XD07 and XL07Z.

[2] Because long-term drift cannot be measured on the individual devices before shipment, this specification is not intended to be a warranty. This specification is an engineering estimate of the averaged trend line of drift versus time over extended periods after the first 30 days of operation.



5.6. Typical Charateristic

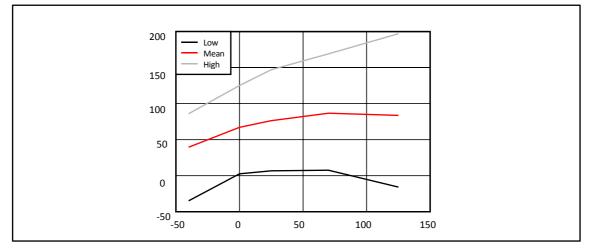


Figure 5-1. Input-Offset Voltage vs Temperature



6. Detailed Description

6.1. Overview

These devices offer low offset and long-term stability by means of a low-noise, chopperless, bipolar-input- transistor amplifier circuit. For most applications, external components are not required for offset nulling and frequency compensation. The true differential input, with a wide input-voltage range and outstanding common- mode rejection, provides maximum flexibility and performance in high-noise environments and in noninverting applications. Low bias currents and extremely high input impedances are maintained over the entire temperature range.

These devices are characterized for operation from -40°C to 85°C.

6.2. Application Information

The input offset voltage of operational amplifiers (op amps) arises from unavoidable mismatches in the differential input stage of the op-amp circuit caused by mismatched transistor pairs, collector currents, current- gain betas (β), collector or emitter resistors, and so on. The input offset pins allow the designer to adjust for these mismatches with external circuitry. Figure 4 shows how these input mismatches can be adjusted by putting resistors or a potentiometer between the null pins. Use a potentiometer to fine tune the circuit during testing or for applications that require precision offset control. For more information about designing using the input-offset pins, see the Nulling Input Offset Voltage of Operational Amplifiers application report.

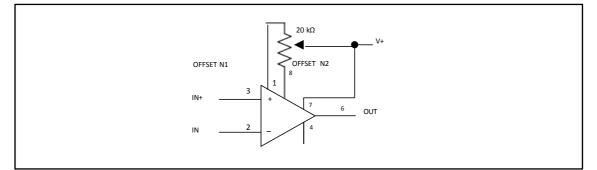


Figure 6-1. Input Offset-Voltage Null Circuit



6.3. Typical Application

The voltage follower configuration of the operational amplifier is used for applications where a weak signal is used to drive a relatively high current load. This circuit is also called a buffer amplifier or unity gain amplifier. The inputs of an operational amplifier have a very high resistance that puts a negligible current load on the voltage source. The output resistance of the operational amplifier is almost negligible, so the amplifier can provide as much current as necessary to the output load.

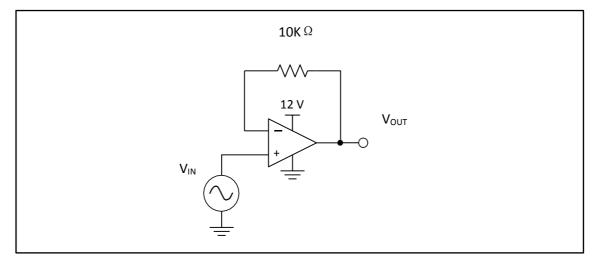


Figure 6-2. Voltage Follower Schematic

6.3.1. Design Requirements

- Output range of 2 V to 11 V
- Input range of 2 V to 11 V

6.3.2. Output Voltage Swing

The output voltage of an operational amplifier is limited by the internal circuitry to some level less than the supply rails. For this amplifier, the output voltage swing is within ± 12 V, which accommodates the input and output voltage requirements.

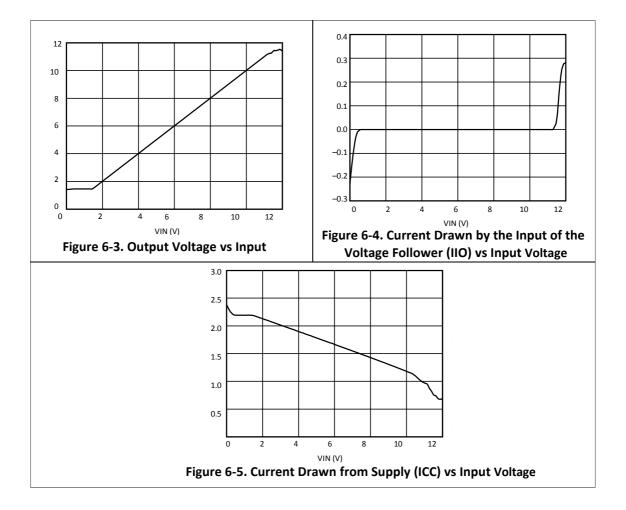
6.3.3. Supply and Input Voltage

For correct operation of the amplifier, neither input must be higher than the recommended positive supply rail voltage or lower than the recommended negative supply rail voltage. The chosen amplifier must be able to operate at the supply voltage that accommodates the inputs. Because the input for this application goes up to 11 V, the supply voltage must be 12 V. Using a negative voltage on the lower rail, rather than ground, allows the amplifier to maintain linearity for inputs below 2 V.





6.3.4. Application Curves



6.4. Power Supply Recommendations

The XL07x operate from ±3 V to ±18 V supplies; many specifications apply from -40°C to 85°C.

CAUTION

Supply voltages larger than ±20 V can permanently damage the device. See also Section 5.1.

Place $0.1-\mu F$ bypass capacitors close to the power-supply pins to reduce errors coupling in from noisy or high-impedance power supplies. For more details on bypass capacitor placement.

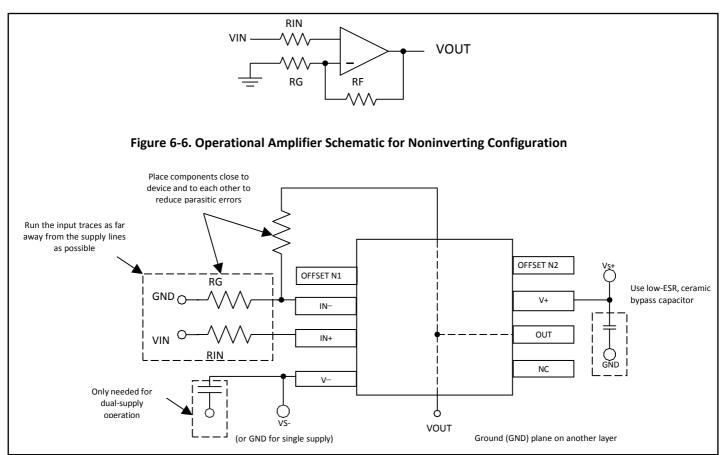


6.5. Layout

6.5.1. Layout Guidelines

For best operational performance of the device, use good PCB layout practices, including:

- Noise can propagate into analog circuitry through the power pins of the circuit as a whole, as well as the operational amplifier. Bypass capacitors are used to reduce the coupled noise by providing low-impedance power sources local to the analog circuitry.
 - Connect low-ESR, 0.1-µF ceramic bypass capacitors between each supply pin and ground, placed as close to the device as possible. A single bypass capacitor from V+ to ground is applicable for single supply applications.
- Separate grounding for analog and digital portions of circuitry is one of the simplest and mosteffective methods of noise suppression. On multilayer PCBs, one or more layers are usually devoted to ground planes. A ground plane helps distribute heat and reduces EMI noise pickup. Make sure to physically separate digital and analog grounds, paying attention to the flow of the ground current.
- To reduce parasitic coupling, run the input traces as far away from the supply or output traces as possible. If it is not possible to keep them separate, it is much better to cross the sensitive trace perpendicularly, as opposed to in parallel, with the noisy trace.
- Place the external components as close to the device as possible. Keeping RF and RG close to the inverting input minimizes parasitic capacitance.
- Keep the length of input traces as short as possible. Always remember that the input traces are the most sensitive part of the circuit.
- Consider a driven, low-impedance guard ring around the critical traces. A guard ring can significantly reduce leakage currents from nearby traces that are at different potentials.



6.5.2. Layout Example

Figure 6-7. Operational Amplifier Board Layout for Noninverting Configuration

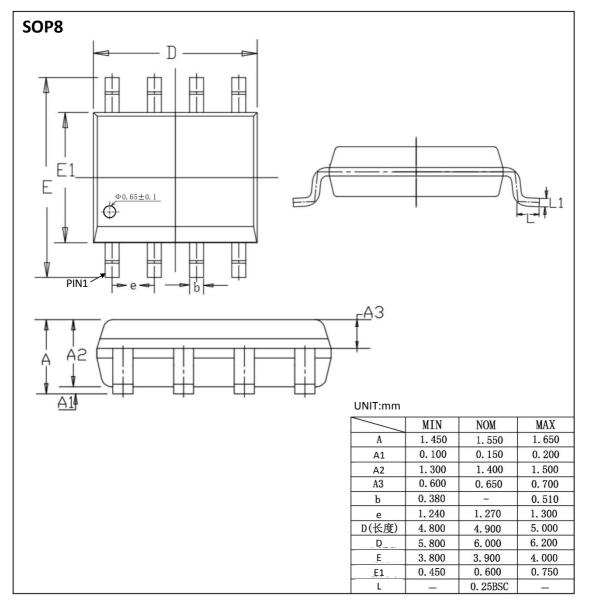


7. ORDERING INFORMATION

Part Number	Device Marking	Package Type	Body size (mm)	Temperature (°C)	MSL	Transport Media	Package Quantity
XL07Z	XL07Z	SOP8	4.90 * 3.90	-40 to +85	MSL3	T&R	2500
XD07	XD07	DIP8	9.25 * 6.38	-40 to +85	MSL3	Tube 50	2000

Ordering Information

8. DIMENSIONAL DRAWINGS



DIP8				
	UNIT:mm	MIN	NOM	MAX
	A	3. 600	3. 800	4.000
	A1	3. 786	3.886	3.986
	A2	3. 200	3. 300	3. 400
	A3	1.550	1.600	1.650
	b	0. 440	-	0. 490
	е	2.510	2.540	2.570
	D	9.150	9. 250	9. 350
	E	7.800	8.500	9.200
	E1	6.280	6.380	6. 480
	L	3.000	—	_

if you need help contact customer service staff Xinluda reserves the right to change the above information without prior notice